



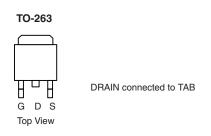
N-Channel 60-V (D-S), 175 °C MOSFET, Logic Level

PRODUCT SUMMARY				
V _{(BR)DSS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A)		
60	0.016 at V _{GS} = 10 V	50		
	0.022 at V _{GS} = 4.5 V	43		

FEATURES

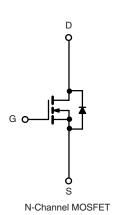
- TrenchFET® Power MOSFET
- 175 °C Junction Temperature





Ordering Information: SUM50N06-16L

SUM50N06-16L-E3 (Lead (Pb)-free)



ABSOLUTE MAXIMUM RATINGS	$T_C = 25 ^{\circ}C$, unless oth	erwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C	1-	50		
	T _C = 100 °C	l _D	35		
Pulsed Drain Current		I _{DM}	100	_ A	
Avalanche Current		I _{AR}	40	1	
Repetitive Avalanche Energy ^a	L = 0.1 mH	E _{AR}	80	mJ	
Power Dissipation	T _C = 25 °C	В	93 ^b	14/	
	T _A = 25 °C ^c	P _D	3.7 ^c	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	(PCB Mount) ^c	R _{thJA}	40	°C/W	
Junction-to-Case		R _{thJC}	1.6]	

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. Surface mounted on FR4 Board, $t \le 10 \text{ s.}$

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			- V
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{DS} = 250 \mu A$	1.0	2.0	3.0	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			150	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α
Drain-Source On-State Resistance ^a		V _{GS} = 10 V, I _D = 20 A		0.013	0.016	Ω
	_	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 125 ^{\circ}\text{C}$			0.028	
	r _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 175 ^{\circ}\text{C}$			0.036	
		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.017	0.022	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		50		S
Dynamic ^b	•					
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		1325		pF
Output Capacitance	C _{oss}			265		
Reverse Transfer Capacitance	C _{rss}			115		
Total Gate Charge ^c	Qg			25	40	nC
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		5.5		
Gate-Drain Charge ^c	Q_{gd}			6.5		
Turn-On Delay Time ^c	t _{d(on)}			10	20	ns
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, R_L = 0.8 \Omega$ $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.5 \Omega$		9	20	
Turn-Off Delay Time ^c	t _{d(off)}			25	50	
Fall Time ^c	t _f			7	15	
Source-Drain Diode Ratings and Cha	aracteristics T	_C = 25 °C ^b		1		
Continuous Current	I _S				50	A
Pulsed Current	I _{SM}				100	
Forward Voltage ^a	V _{SD}	I _F = 50 A, V _{GS} = 0 V		1.0	1.5	V
Reverse Recovery Time	t _{rr}			35	70	ns
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, di/dt = 100 A/μs		2.3	4	Α
Reverse Recovery Charge	Q _{rr}			0.04	0.14	μС

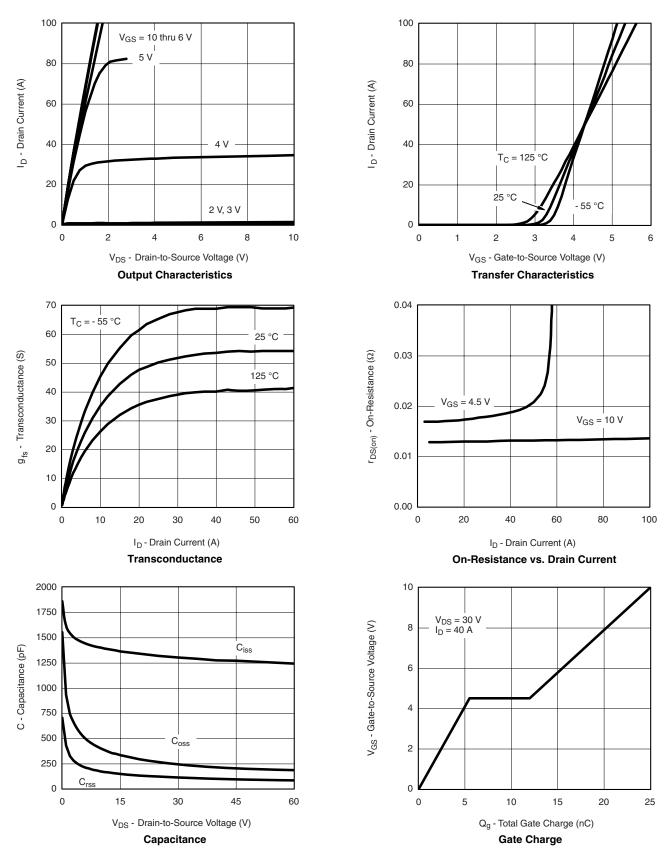
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



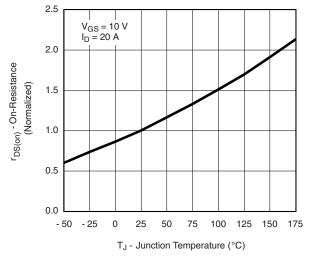
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



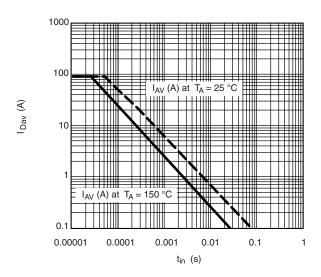
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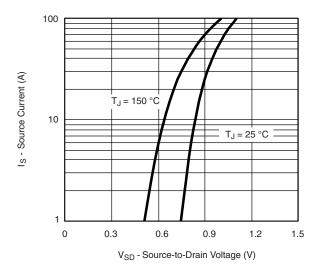
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

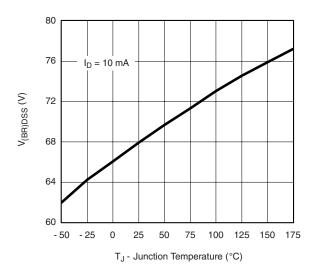


On-Resistance vs. Junction Temperature





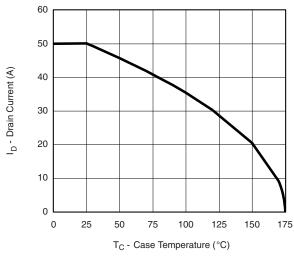
Source-Drain Diode Forward Voltage



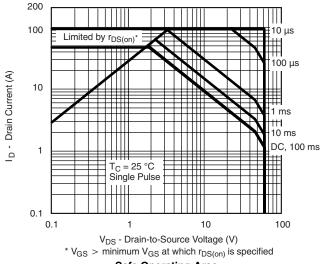
Drain Source Breakdown vs. Junction Temperature



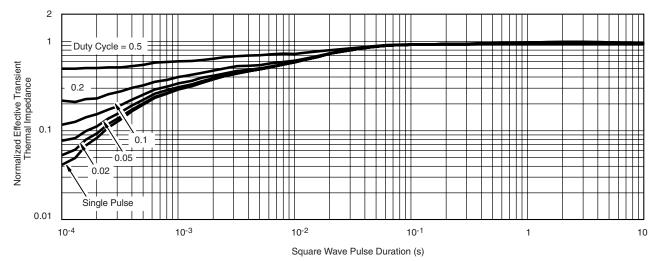
THERMAL RATINGS



Drain Current vs. Case Temperature







Normalized Thermal Transient Impedance, Junction-to-Case

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